

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|-----------------|----------------|--|------------|--------------|-------------------------|---------------|
| Die | Metal oxide | Lead Dioxide (PbO2) | 1309-60-0 | 0.03 | 2.63 | 0.09 |
| | Doped silicon | Silicon (Si) | 7440-21-3 | 0.94 | 97.37 | 3.21 |
| Subtotal | | | | 0.97 | 100 | 3.3 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 3.51 | 100.0 | 12 |
| Subtotal | | | | 3.51 | 100 | 12 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.02 | 0.03 | 0.05 |
| | Copper alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.02 | 0.03 | 0.05 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.05 | 0.1 | 0.17 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 50.94 | 99.84 | 173.92 |
| Subtotal | | | | 51.03 | 100 | 174.19 |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 2.62 | 6.0 | 8.96 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 3.06 | 7.0 | 10.45 |
| | Filler | Silica fused | 60676-86-0 | 37.61 | 86.0 | 128.4 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.44 | 1.0 | 1.49 |
| Subtotal | | | | 43.73 | 100 | 149.3 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.23 | 100.0 | 0.8 |
| Subtotal | | | | 0.23 | 100 | 0.8 |
| Die Attach | Lead alloy | Tin (Sn) | 7440-31-5 | 0.01 | 2.0 | 0.04 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.01 | 2.5 | 0.05 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.51 | 95.5 | 1.74 |
| Subtotal | | | | 0.53 | 100 | 1.83 |
| Total | | | | 100 | 100 | 341.42 |

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